

Serial No.10/713,510
HP Docket No: 200308744-1

1. (Currently Amended) A thin film device comprising:
 - at least one patterned thin film layer;
 - a heater material coupled to at least one of the patterned thin film layers for providing thermal assistance thereto wherein the heater material comprises at least one of amorphous silicon and amorphous carbon; and
 - a conductor coupled to the heater material to supply energy to the heater material.
2. (Original) The device of claim 1 wherein the thin film device comprises a magnetic random access memory device.

Please cancel claim 3.

4. (Original) The device of claim 1 wherein the at least one patterned thin film layer is formed on the heater material.
5. (Original) The device of claim 1 wherein the conductor is a split conductor and the heater material is connected between the split conductor.
6. (Original) The device of claim 1 wherein the energy comprise radio frequency energy.
7. (Original) The device of claim 2 wherein the at least one patterned thin film layer comprises a magnetic memory element.

Please cancel claim 8.

Serial No.10/713,510
HP Docket No: 200308744-1

9. (Original) The device of claim 4 wherein the heater material comprises a metal.

10. (Original) The device of claim 5 wherein the conductor comprises a conductive sidewall material comprising at least one of Cu, Au, Ag, Pt, Al.

11. (Currently Amended) The device of claim 6 7 wherein the magnetic memory element comprises at least one of a spin dependent tunnel junction and a giant magnetoresistive device.

12. (Currently Amended) The device of claim 6 7 wherein the magnetic memory element includes a free layer and the heater material provides thermal assistance in switching a magnetic orientation of the free layer.

13. (Original) The device of claim 6 wherein the at least one patterned thin film layer is formed over a dielectric material and the dielectric material is in contact with the heater material.

14. (Original) The device of claim 10 wherein the conductive side wall material is coupled to a power source.

15. (Original) The device of claim 14 wherein the conductive side wall material is coupled to the power source via a decoder.

16-30. Previously Canceled.

31. (Currently Amended) A computer system comprising:

a processor;

an interface module coupled to the processor; and

a magnetic random access memory device coupled to the interface module

wherein the magnetic random access memory device includes a plurality of magnetic

Serial No. 10/713,510
HP Docket No: 200308744-1

memory elements, a heater material coupled to at least one of the plurality of magnetic memory elements for providing thermal assistance in switching a magnetic orientation of the at least one of the plurality of magnetic memory elements and a conductor coupled to the heater material for supplying energy to the heater material wherein the conductor is a split conductor and the heater material is connected between the split conductor.

32. (Original) The computer system of claim 31 wherein each of the plurality of magnetic memory elements comprises a spin dependent tunneling junction.

33. (Original) The computer system of claim 31 wherein each of the plurality of magnetic memory elements is formed on the heater material.

34. (Original) The computer system of claim 33 wherein the heater material comprises amorphous carbon.

35. (Original) The computer system of claim 33 wherein the heater material comprises amorphous silicon.

36. (Original) The computer system of claim 33 wherein the heater material is coupled to a conductive sidewall material wherein the conductive sidewall material comprises at least one of Cu, Au, Ag, Pt, Al.

37. (Original) The computer system of claim 36 wherein the heater material is formed in between the conductive sidewall material.

38. (Currently Amended) A magnetic random access memory device comprising:
a plurality of magnetic memory elements;
a heater material coupled to at least one of the plurality of magnetic memory elements wherein the heater material comprises at least one of amorphous carbon and amorphous silicon;

Serial No.10/713,510
HP Docket No: 200308744-1

a decoder coupled to the heater material; and
a radio frequency power source coupled to the decoder for providing heat to the
heater material to thermally assist in switching a magnetic orientation of the at least one
of the plurality of magnetic memory elements.

39. (New) A thin film device comprising:
at least one patterned thin film layer;
a heater material coupled to at least one of the patterned thin film layers
for providing thermal assistance thereto; and
a conductor coupled to the heater material to supply energy to the heater
material wherein the conductor is a split conductor and the heater material is connected
between the split conductor.